



# FRONTGRADE

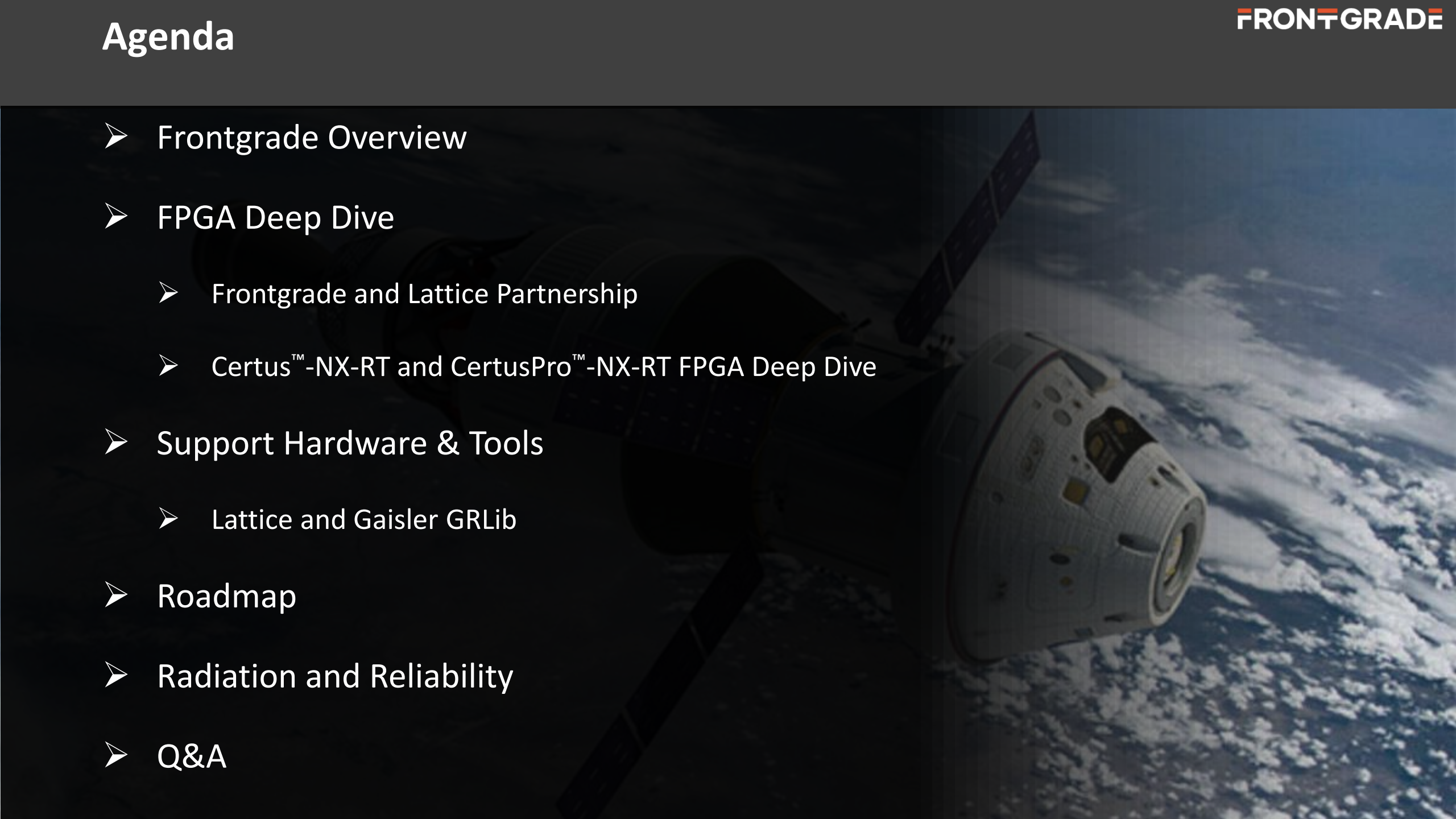
## Innovating At The Speed Of Technology

Next-Gen FPGAs For Space

March, 2023

David Meyouhas – Sr Director of Standard Products  
Brian Baranski – Systems Architect

Frontgrade Technologies Public

- Frontgrade Overview
  - FPGA Deep Dive
    - Frontgrade and Lattice Partnership
    - Certus™ -NX-RT and CertusPro™ -NX-RT FPGA Deep Dive
  - Support Hardware & Tools
    - Lattice and Gaisler GRLib
  - Roadmap
  - Radiation and Reliability
  - Q&A
- 
- A background image showing a spacecraft in orbit above Earth's cloud-covered surface. The spacecraft is dark and partially obscured by shadows, with a white conical structure visible in the foreground.

A night landscape photograph showing a dark road winding through a snowy, mountainous terrain under a starry sky. The Milky Way is visible in the dark blue sky. The image is partially obscured by a dark grey overlay on the right side.

**FRONTGRADE**

# Frontgrade Overview



- Frontgrade is a stand-alone Company serving Space, Defense and Commercial customers with advanced electronic solutions
- Frontgrade pioneers new technology leveraging decades of heritage in the harshest domains
- Veritas Capital acquired the Space Systems Division of CAES from Advent International in January 2023
- Over 1,100 employees across the US and Europe
- Frontgrade is headquartered in Colorado Springs USA, and is comprised of five sites



# Frontgrade – Microelectronics History



**1980**

**1980**  
United Technologies  
Microelectronics  
Center (UTMC)  
founded

**1998**

**1998**  
UTMC acquired by  
Aeroflex

**2008**

**2008**  
Aeroflex acquires Gaisler  
Research

**2014**

**2014**  
Aeroflex acquired  
by Cobham

**2020-2021**

**2020**  
Acquired by Advent  
International and  
rebranded as CAES


**2023**

**2023**  
Acquired by Veritas  
Capital and rebranded  
as Frontgrade


## Microelectronics

  
*Microprocessors*

  
*Microcontrollers*

  
*Logic / FPGA*

  
*ASIC Design*

  
*Packaging & Test*

  
*Single Board Computer*

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**Rad-Hard Components:**

- FPGA
- Microprocessors
- Microcontrollers
- Memory
- Interconnects

**Custom ASICs:**

- ASIC design
- Packaging & test

**Mission Processing:**


- Single board computer
- Box design & assembly
- Manufacturing


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**Major Sites:**


- Colorado Springs, CO (two facilities)
- Gothenburg, Sweden


## Electro-Mechanical Systems


  
*Waveguides*


  
*Cables*

  
*Rotary Joints*

  
*Steerable*

  
*Non-Steerable*

  
*Motion Control*

  
*Slotted Flat Panel*

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**RF Transmission:**

- Waveguides
- Cables
- Rotary joints

**Antennas:**

- Steerable antennas
- Non-steerable antennas
- Slotted flat panel

**Motion Control:**


- Motion control products
- Satellite solar panel actuation
- Mars Rover arm actuation
- Optical steering


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**Major Sites:**


- Exeter, NH
- Hauppauge, NY


## Power Solutions

  
*Converters*

  
*Battery Electronics*

  
*Synthesizers*

  
*Hybrids*

  
*Modules*

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**Power Management:**

- Converters
- Modules
- Battery electronics
- Hybrids

**RF Generation:**

- Synthesizers

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**Major Sites:**

- Plainview, NY

A night landscape photograph showing a dark road winding through a snowy, mountainous terrain. The sky is filled with stars, and a faint orange glow is visible on the horizon. The image is split diagonally, with the left side showing the landscape and the right side being a dark grey background with text.

# FRONTGRADE

## FPGA Deep Dive

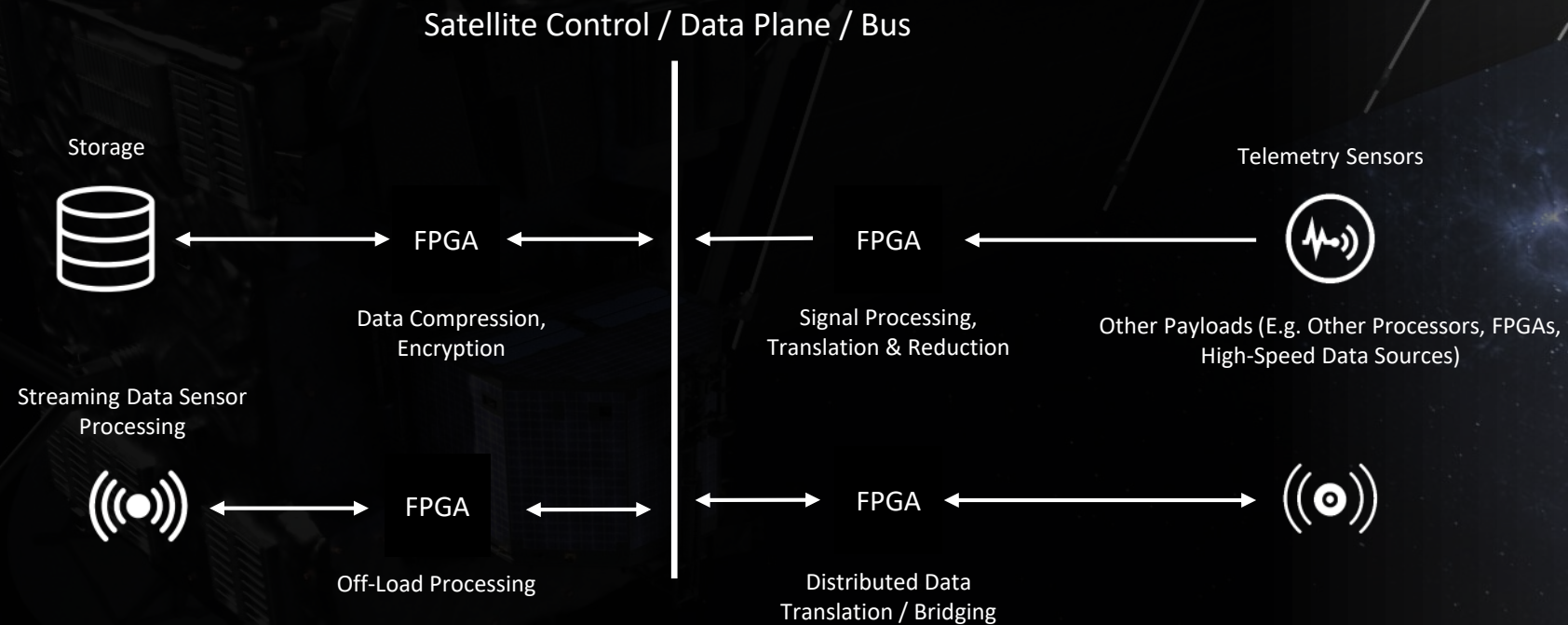


# Scalable, High-Reliability Distributed Processing

Making Satellites Multi-Functional, Reconfigurable and Autonomous

Space engineers need versatile, reliable processing solutions that are easy to use and scale

- Inter-box comms, data translation and bridging
- Robotics and motor control
- Distributed sensor processing and platform management
- Off-load processing



Versatility / performance has made FPGAs the indispensable distributed processing building block

# When Small FPGAs and Microcontrollers Are Not Enough

And Large FPGAs Are Overkill

Performance

Large FPGAs  
and Processors



Xilinx KU060



Microchip RTG4



Microchip RT  
Polarfire



Xilinx  
Versal

FPGAs for Distributed  
Space Processing

Small FPGAs  
and Microcontrollers



Vorago  
VA41630



Microsemi RT  
ProASIC3



Microchip  
RTAX

SWaP-C

Frontgrade, the leading electronics space products provider and Lattice, the low power programmable leader are solving the space industry's need for efficient FPGAs

# Frontgrade and Lattice

Why Our Partnership Matters

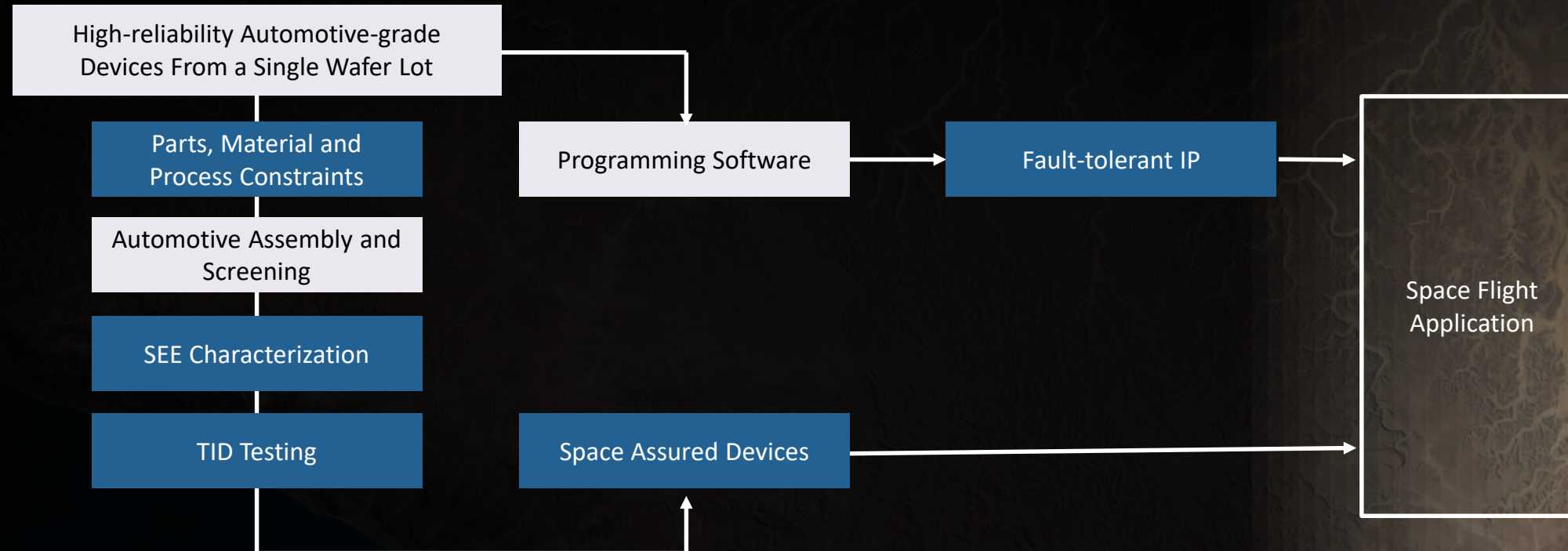
The logo for Frontgrade, featuring the word "FRONTGRADE" in a bold, white, sans-serif font. The letter "T" is stylized with a horizontal bar through it. There are orange horizontal bars above the "F", "O", and "E".The logo for Lattice Semiconductor, featuring the word "LATTICE" in a bold, white, sans-serif font above the word "SEMICONDUCTOR" in a smaller, yellow, sans-serif font. To the left of the text is a yellow graphic consisting of a grid of squares.

- Leading dedicated space electronics provider
- 30 years space flight heritage
- Flight-proven space-grade QCOTS, QML-Q and QML-V processing flow assurance
- Low power programmable device leader
- 20 years automotive domain expertise
- Industry leading performance and reliability

Our proven space heritage and the latest commercially developed FPGA technology will supercharge next-gen services in support of government, civil & commercial missions

# The Latest Commercially Developed Technology

For Space Missions



## Lattice

- FPGA based on inherently resilient 28nm FDSOI technology
- Design and manufacture commercial devices
- Specially built FPGA lots for radiation testing

## Frontgrade

- Tightly coupled interaction with Lattice manufacturing & source
- Radiation assurance
- Augment SW with fault-tolerant libraries
- Device traceability

# Engaging With Frontgrade

## What We Are Delivering



- Space flight assurance
  - Packaging for flight: SnPb balling
  - Single wafer lot traceability
  - Radiation lot acceptance testing
  - Radiation reports
  - NASA out-gassing compliance
  - Flight assurance expertise
- Design-in and technical support from program start to finish
  - Development kits
  - Fault-tolerant IP
  - Easy access to engineering support
- Comprehensive HW and design SW ecosystem
- Long-term assured supply

## Inherently Radiation Tolerant FD-SOI Technology Upscreened For Space Flight

Our space flight heritage expertise adds assurance to the insertion of best automotive technology



### Technology Assurance

- Total ionizing dose (TID) and single event effects (SEE) testing
- Thorough SEE testing and evaluation

### Wafer/Die Integrity and Manufacturing Process Traceability

- Single homogenous wafer lot traceability from source to delivery
- Silicon design revision and fabrication process revision tracking

### Data Sharing Transparency and Program Support

- Extensive characterization TID and single event fault interrupts, effects, gate rupture, upsets and latch-up data packs and analysis available
- Program support from start-to-finish from experienced space and FPGA experts
- QCI summary available with each lot

# Better Technology

Radiation Resilient, SWaP-Efficient, High Performance



Reliable, fully depleted silicon on insulator (FD-SOI) fabrication technology is a planar process that is ideally aligned to modern space missions



Designed by Lattice, The Low Power Programmable Leader with the performance, features and bandwidth required for modern embedded processing



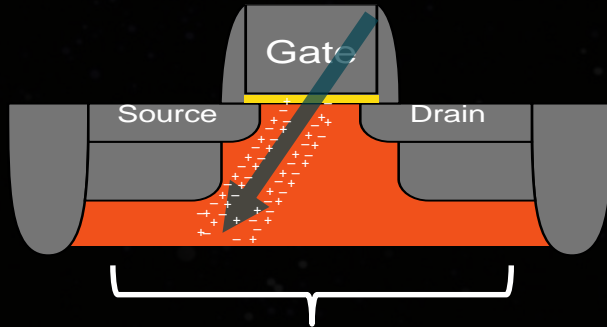
28nm technology provides greater processing density and reduced size, weight, and power consumption

Inherently radiation tolerant architecture minimizes SEUs, and is augmented with built-in error detection and correction features

# FD-SOI Is Inherently Radiation Tolerant

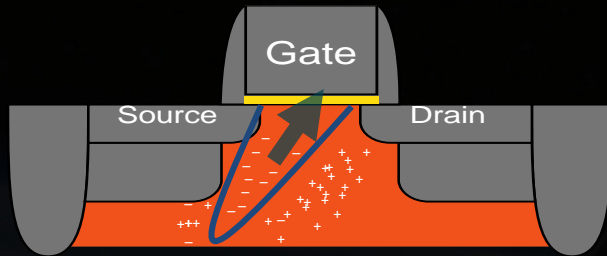
## Effect of Ionizing Particles

### Traditional FPGA on Bulk

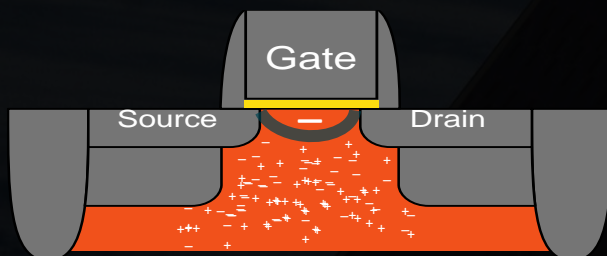


Radiation strike ionizes Si atoms, forming cylindrical track of electron hole pairs

Critical transistor channel area (orange) for soft errors (several  $\mu\text{m}$  thick)

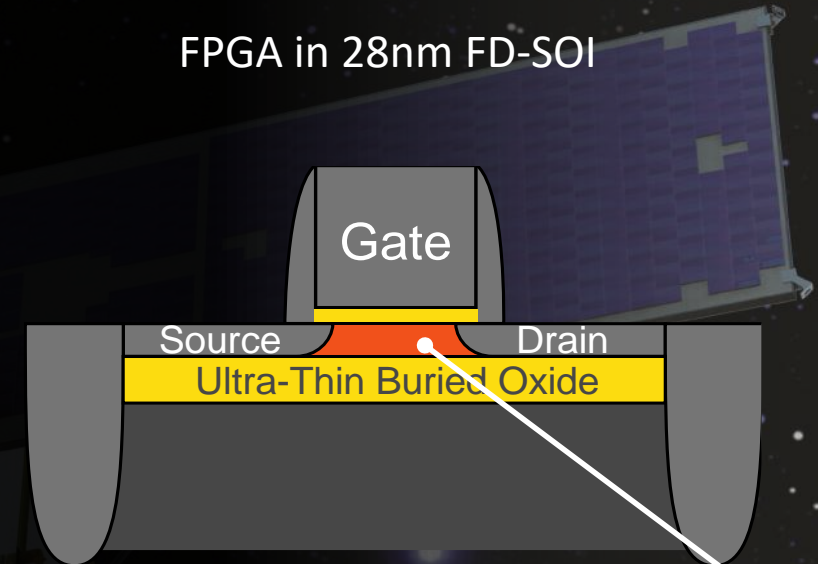


Funnel-shaped charge collection occurs



Charge collects into current pulse, state of charge inverts

### FPGA in 28nm FD-SOI



Silicon film transistor channel ( $\sim 100 \text{ \AA}$ )

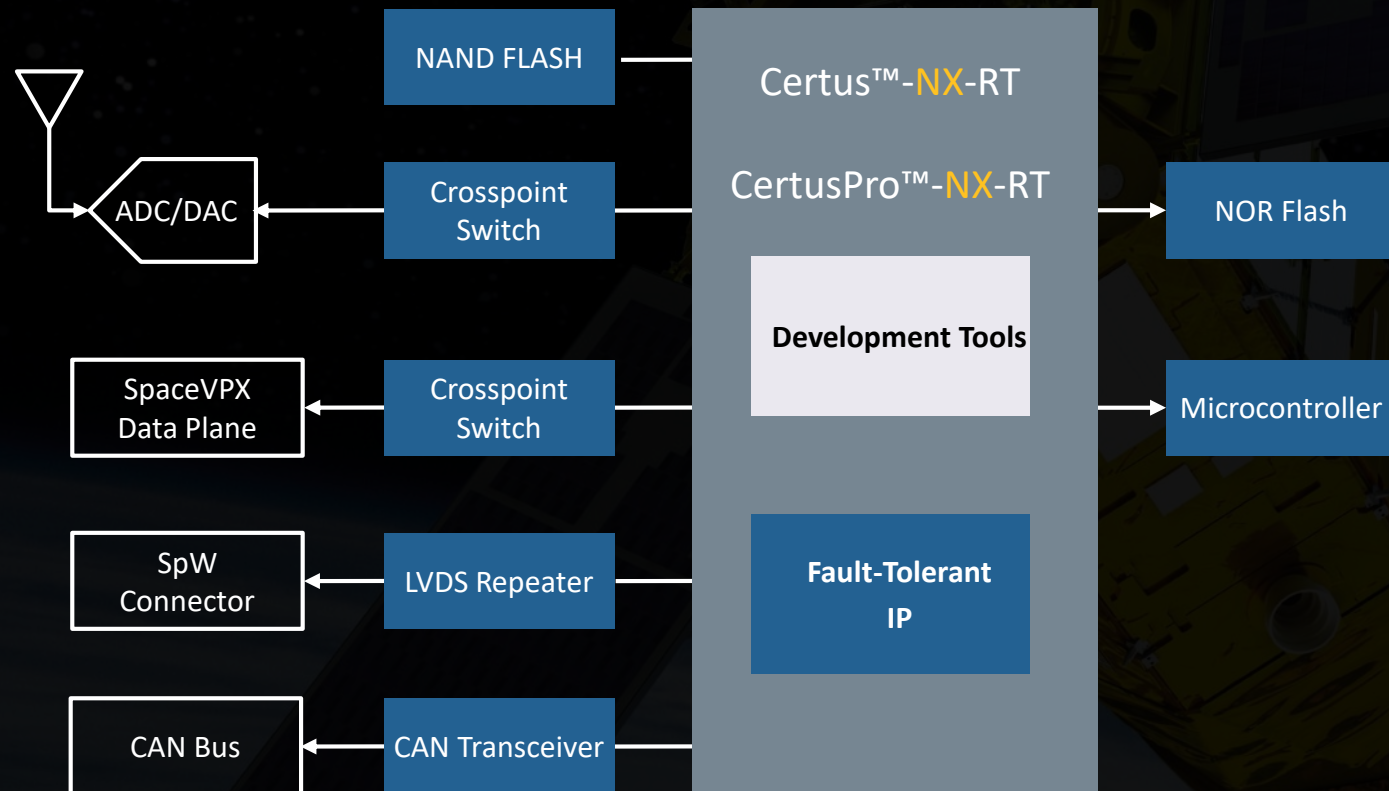
- Critical area significantly reduced, minimizing charge collection
- Built-in SEC (fabric SRAM) and ECC (EBR & large RAM) for added mitigation
- Greatly improved soft error rate (SER)



# Comprehensive Ecosystem

## Hardware

Full suite of SWaP optimized peripheral devices, all with space flight assurance



- Interoperable and proven
- Highest through-put and densities
- Reference design & engineering support
- Long-term assured supply

# Certus™-NX-RT and CertusPro™-NX-RT

Filling the Performance / SWaP-C Gap For Distributed Satellite Processing

	Certus-NX-RT	CertusPro-NX-RT
Technology	28nm FD-SOI	28nm FD-SOI
Logic Cells	39K	96K
LUT4/Flip Flop	32.3k	79.9k
Embedded Memory	2.5Mb	7.3Mb
Supply Voltage (V)	1.0 Core, 1.8V Aux	1.0 Core, 1.8V Aux
Maximum Image Size (w/ max. LRAM & EBR)	8.807Mb	22.333Mb
I/O Voltage (V)	1.0 – 3.3	1.0 – 3.3
PLL	3	4
Primary I/O	LVDS, Soft D-PHY, SGMII, PCIe, GbE	LVDS, Soft D-PHY, SGMII, PCIe, 10GbE
SERDES	4 lanes	8 lanes
Supported Memory	DDR2/3L, LPDDR2/3 x8, x16	DDR2/3L, LPDDR2/3/4 x8, x16, x32, x64
Security	Bit stream encryption (AES-256) & authentication (ECDSA)	Bit stream encryption (AES-256) & authentication (ECDSA)
ADC	2x 1 MSPS, 12-bit SAR	2x 1 MSPS, 12-bit SAR
Typical Power (mW)	100	600
Size (mm)	14 x 14, 0.8 pitch	19 x 19, 0.8 pitch
Temp. (°C)	-40 to 125	-40 to 125
Packaging	Plastic package, SnPb balling (x256)	Plastic package, SnPb balling (x484)
TID (kRad (Si))	100	100
SEL immune (MeV-cm <sup>2</sup> /mg)	≤80	≤80
Export Classification	EAR99	3A991.d

Two options to support your needs

# A Closer Look at Certus™-NX-RT

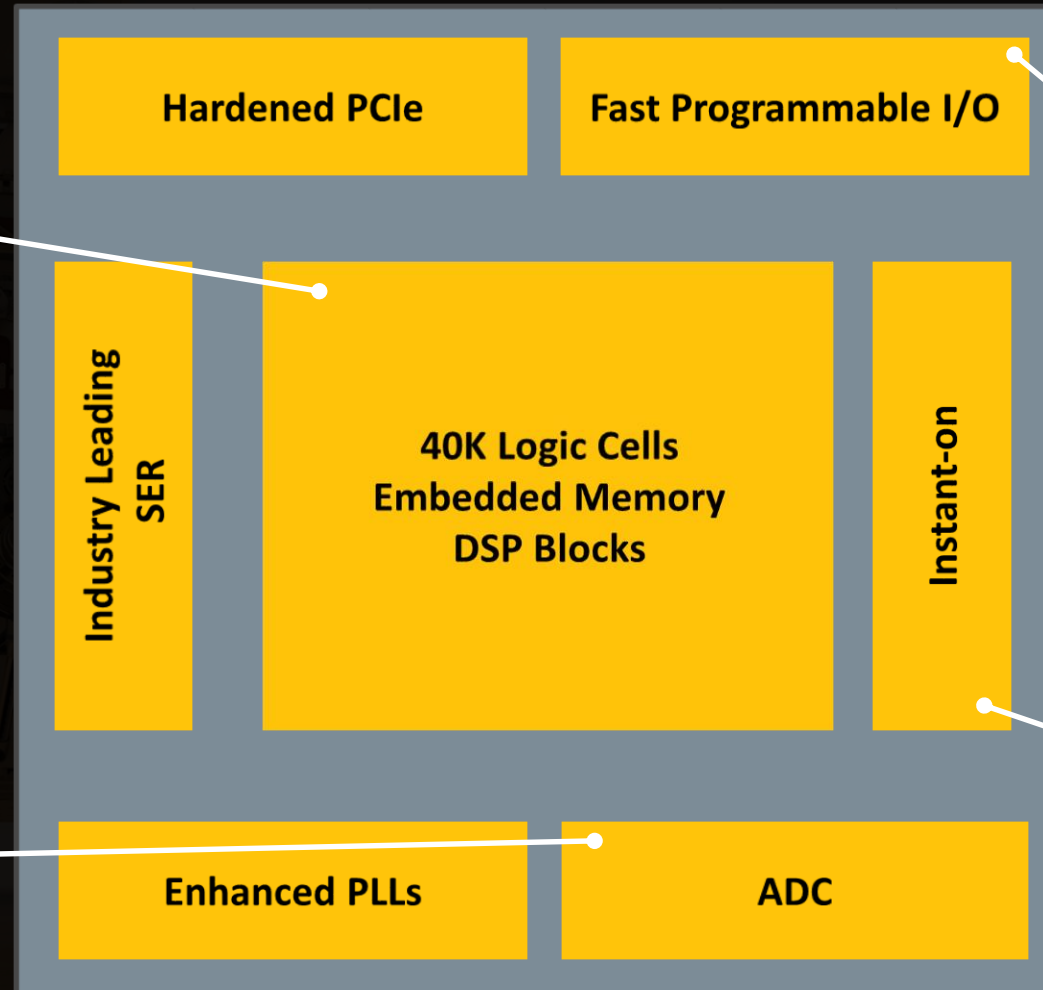
Reinventing the Low-Power General Purpose FPGA For Space

## Programmable Core

- Infinitely reconfigurable
- Low-power mode
- Industry-leading reliability
- High-performance mode
- High embedded memory count
- 56 SysDSP blocks

## Hard Macro Blocks

- One lane PCIe (5 Gbps)
- CDR for SGMII (1.25 Gbps)
- ADC



## Fast Programmable I/O

- Diff I/O (1.5 Gbps)
- LVDS, subLVDS, SGMII
- DDR3 (1066 Mbps)
- 192 total I/O (118 at 3.3V)

## Instant-On

- 3 ms I/O config.
- 15 ms device configuration

# A Closer Look at CertusPro™-NX-RT

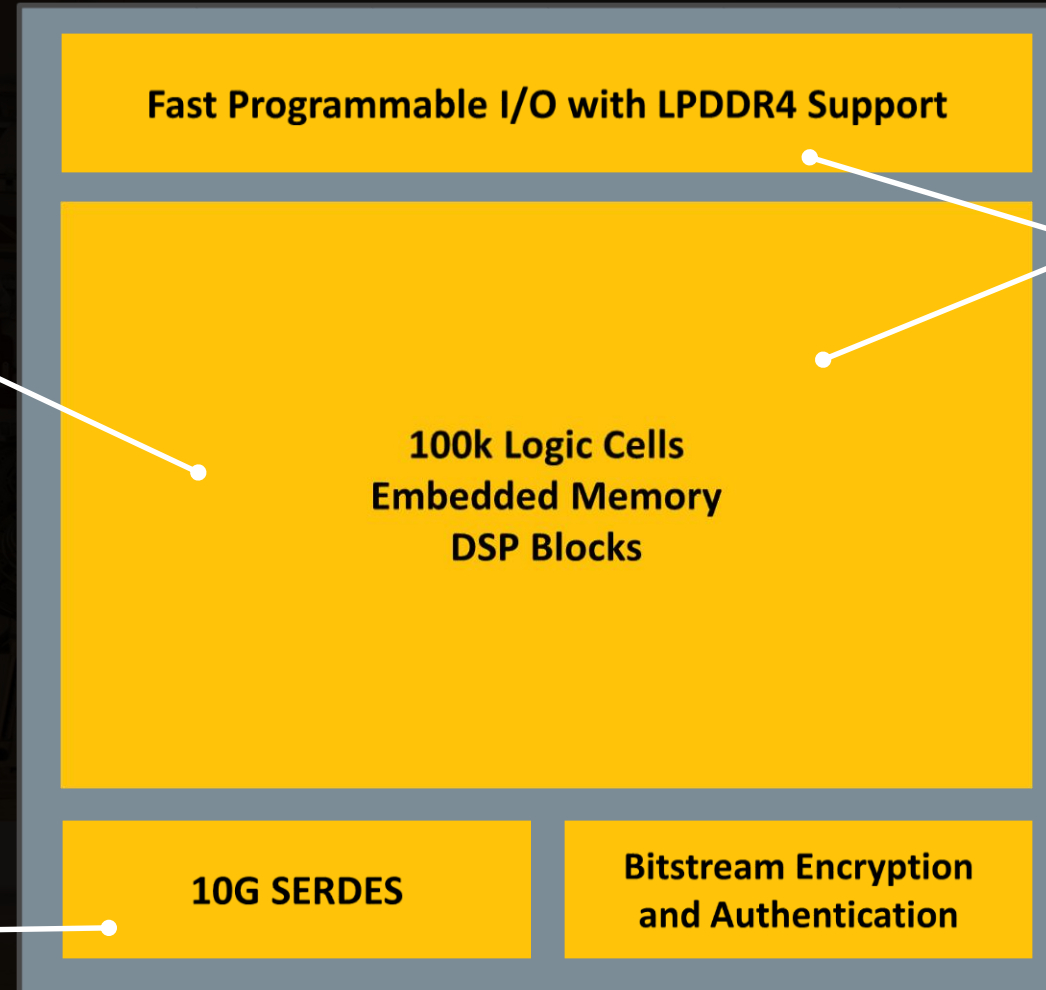
Optimized For Embedded Edge AI Processing

## Low Power FPGA Fabric

- Power efficient performance
- Built on FD-SOI technology
- Industry-leading reliability
- 100k logic cells
- 156 SysDSP blocks

## High Bandwidth Interfaces

- 8 SERDES lanes up to 10 Gbps
- Flexible multi-protocol PCS
- Supports 10GE, PCIe Gen 3 and more



## Optimized For Edge Processing

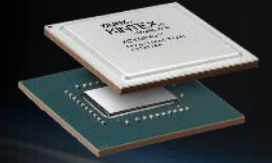
- DSP, LRAM and EBR
- 7.3 Mb on-chip memory
- LPDDR4, DDR3 (1066 Mbps)
- ADC
- 305 total I/O (167 at 3.3V)
- 4ms I/O configuration
- 30 ms device configuration

## Small Form Factor

- 19 x 19 mm package

# Space Grade FPGAs

FD-SOI Delivers Better SWaP Performance For Processing Closer To The Data Source



Microsemi  
RT ProASIC3

NanoXplore  
NG-MEDIUM

Frontgrade / Lattice  
Certus-NX-RT

Frontgrade / Lattice  
CertusPro-NX-RT

Microsemi  
RTG4

Microsemi  
PolarFire

Xilinx  
KU060

Footprint (mm<sup>2</sup>)

576

841

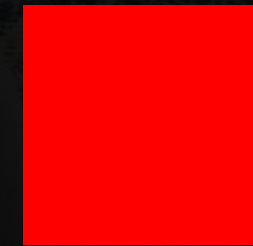
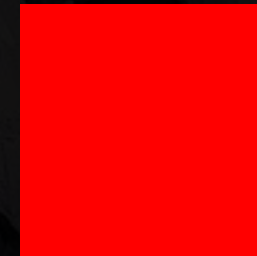
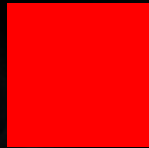
196

361

1,764

1,600

1,600



24 mm

29 mm

14 mm

19 mm

42 mm

40 mm

40 mm

Typical Power (mW)

1,250

1,500

100

600

9,000

5,000

10,000



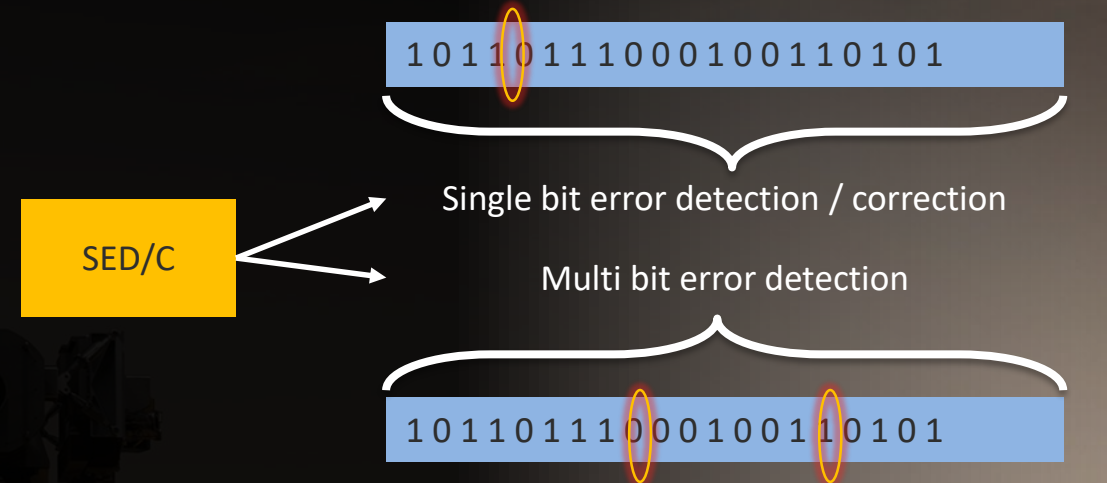
# Competitive Features

	RT ProASIC3	RTAX	NG-Medium	Certus™-NX-RT UT24C407	CertusPro™-NX-RT UT24CP1008	RTG4
Logic Density	14K	25K LE	35K	39K LC	96K LC	150K
Embedded Memory(Mb) <sup>1</sup>	0.1	0.16	2.7	2.5	7.3	5.2
18 x 18 Multipliers	N/A	N/A	112	56	156	462
I/O Count	270	418	192-374	192	305	720
SERDES	N/A	N/A	N/A	x1 PCIe Hard IP(5G) X2 SGMI (1.25G) <sup>2</sup>	8 x 10Gbps	24 x 3.125 Gbps
Configuration / Security	139nm Built-in Flash	150nm, Antifuse(OTP) RHBD	External Flash	External Flash ( with instant-on) / AES-256, ECDSA/HMAC	External Flash ( with instant-on) / AES-256, ECDSA/HMAC	65nm Built-in Flash RHBD
Key Features	1Mb flash ROM, DPA	SEU hardened registers, 5V tolerant I/O	Embedded Spacewire	Lowest power, Smallest package with PCIe & GigE, EDAC	PCIe Gen III, LPDDR4, SGMII, EDAC	SEU hardened register, EDAC, DDR3
Package <sup>3</sup>	B, E class CCGA484 -40 to 155C Temp	B, V class CG624 -40 to 155C Temp	CQFP352, CCGA 625,	256 BGA 0.8mm – 40 to 125C Temp	484 BGA, 0.8mm -40 to 125C Temp	B, V class CCGA1657, -40 to 155C Temp
Static Power	134mW	240mW	871mW	87 mW	220mW	3900mW
DFF operating saturated cross-section	2x10 <sup>-7</sup>	1x10 <sup>-7</sup>	5x10 <sup>-9</sup>	2.7x10 <sup>-8</sup>	2.7x10 <sup>-8</sup>	2x10 <sup>-8</sup>
TID	25krad	200krad parametric, 300krad functional	100krad	100krad parametric, 200krad functional	100krad parametric, 200krad functional	200krad parametric, 300krad functional
SEL	Estimated at 68MeV	Immune to 117 MeV	Immune to 60MeV	Immune to 80MeV	Immune to 80MeV	Immune to 103MeV

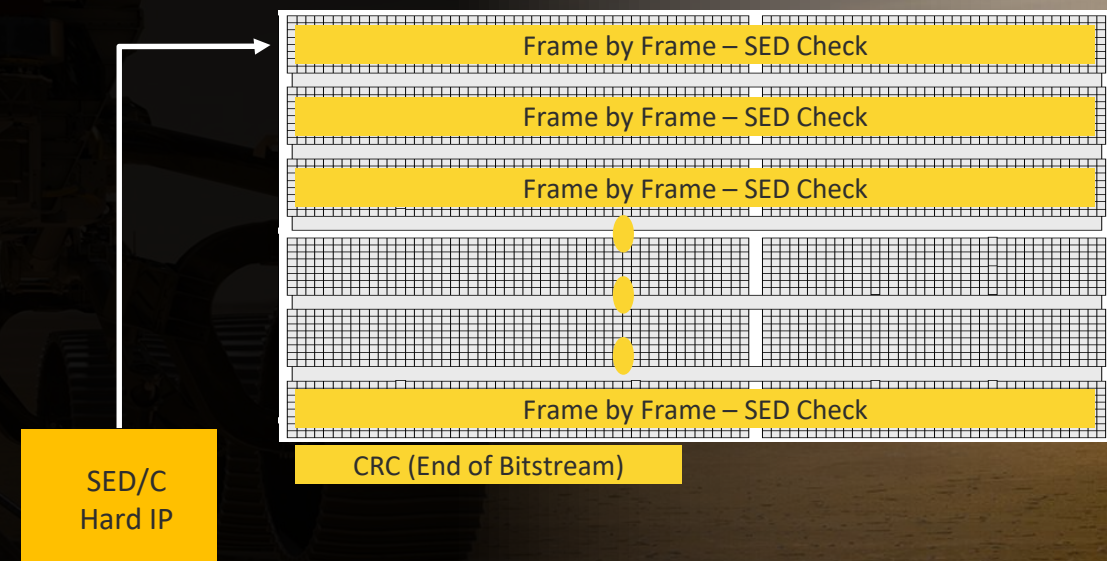
# Soft Error Detection and Correction

Certus™-NX-RT and CertusPro™-NX-RT

- Built-In Error Detection and Correction On All Embedded Memory Bits
- Dedicated hard logic to detect soft errors
- Frame by frame SED check
- Single and multi-bit error detection
- Frame level single bit error correction
- Programmable SED clock with wider clock frequency option
- Soft error injection (SEI) tool available in Radiant



- Two levels of SED check
  - Level 1: Frame level
  - Level 2: Bitstream level
- Frame by Frame SED check
- CRC at the end of bitstream
- Correction using ECC for single bit error
- Multi-bit error detection only
- Report out error location of error frame
- Report out bit location inside the error frame

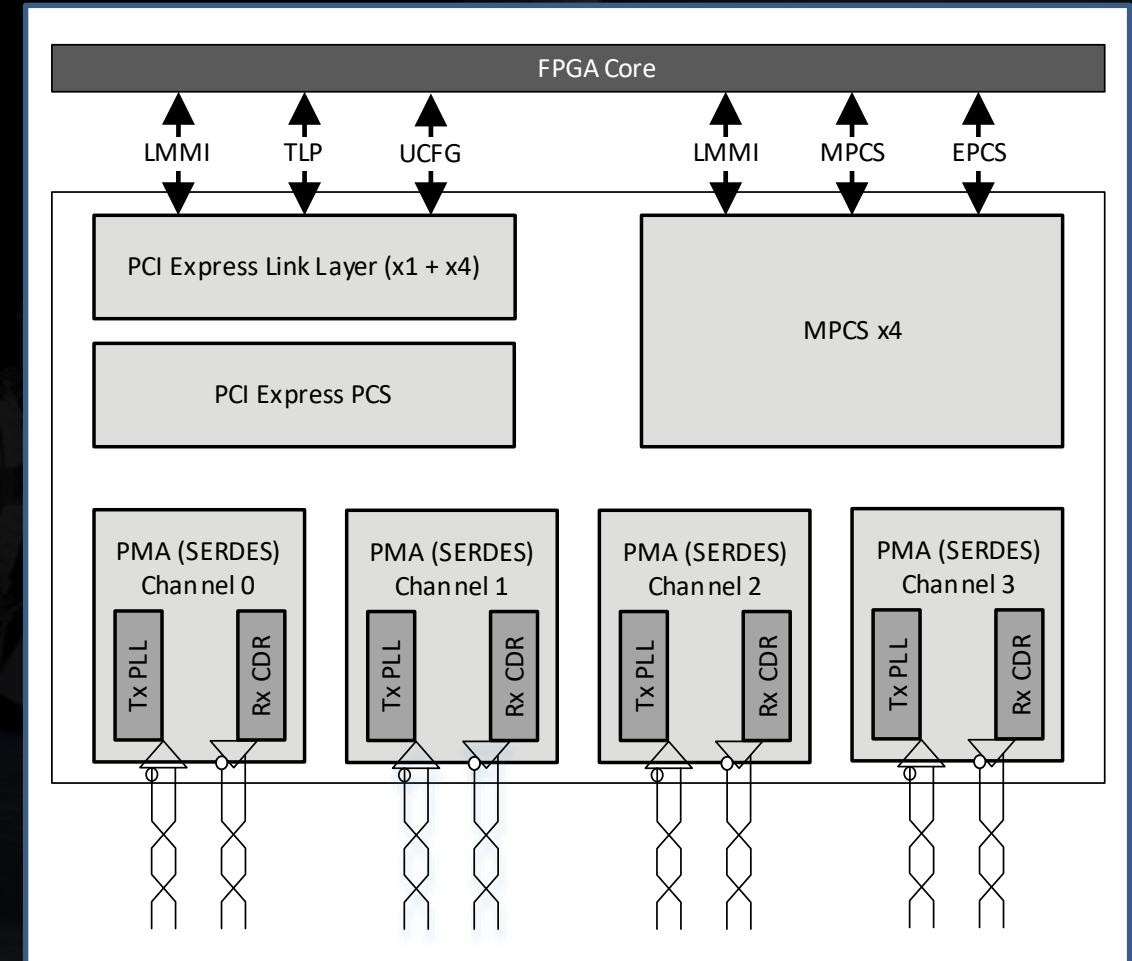


# SerDes Quad

CertusPro™-NX-RT

- CertusPro-NX-RT SerDes/PCS Quad includes
  - Four PMA channels
  - One PCIe PCS
  - One MPCS
  - One PCI Express Link Layer(X4+X1) (Only for the left-most Quad)
- PCI Express PCS is designed for PCI Express only
- MPCS is designed for general protocols
- Below table shows the different mode for the SerDes/PCS feature combination

SerDes/PCS Mode	PCI Express	MPCS	PMA Only	PIPE
PMA	✓	✓	✓	✓
PCI Express PCS	✓	bypass	bypass	✓
PCI Express Link Layer Quad	✓			
MPCS		✓		

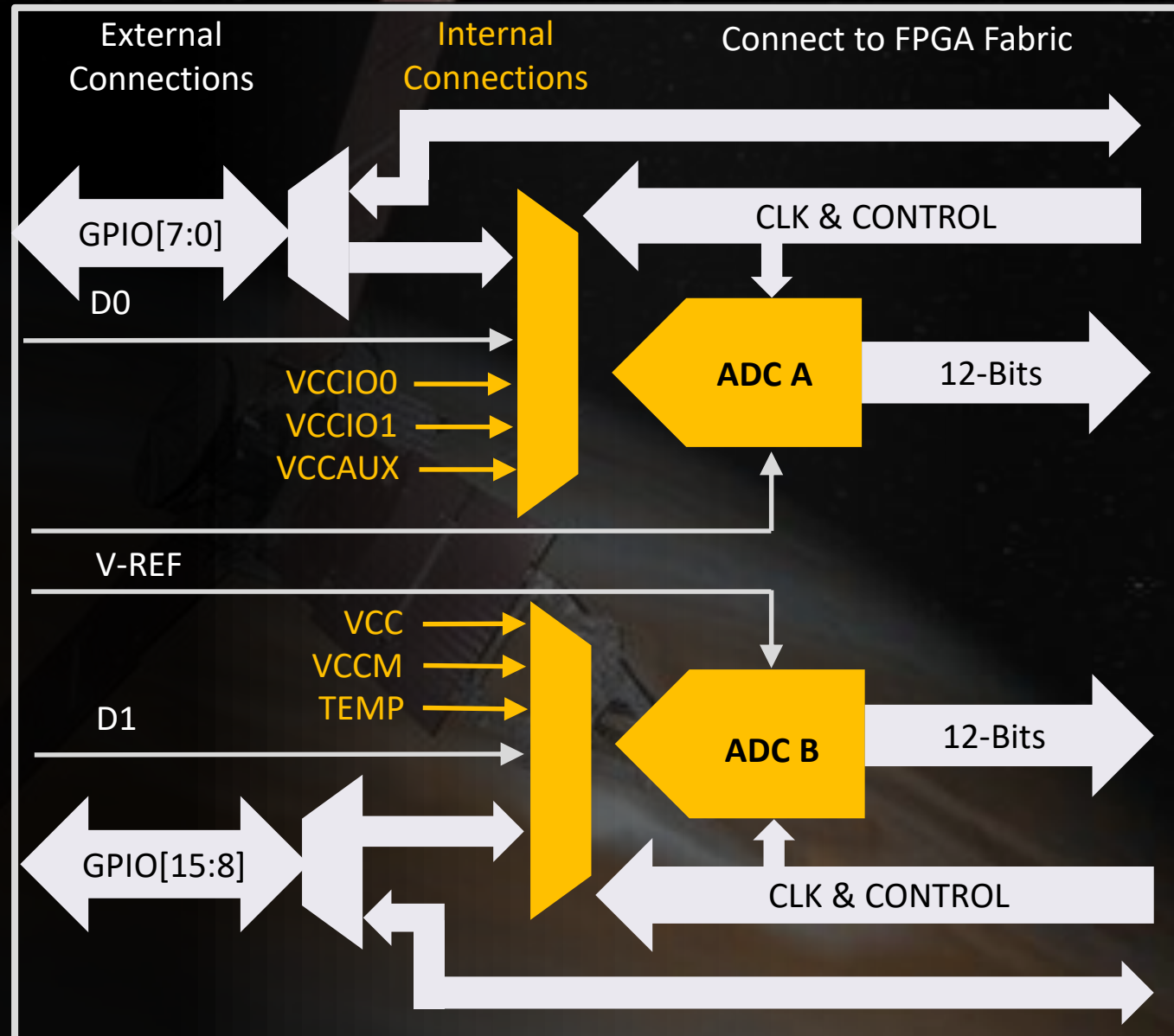




# Embedded ADCs

CertusPro™-NX-RT

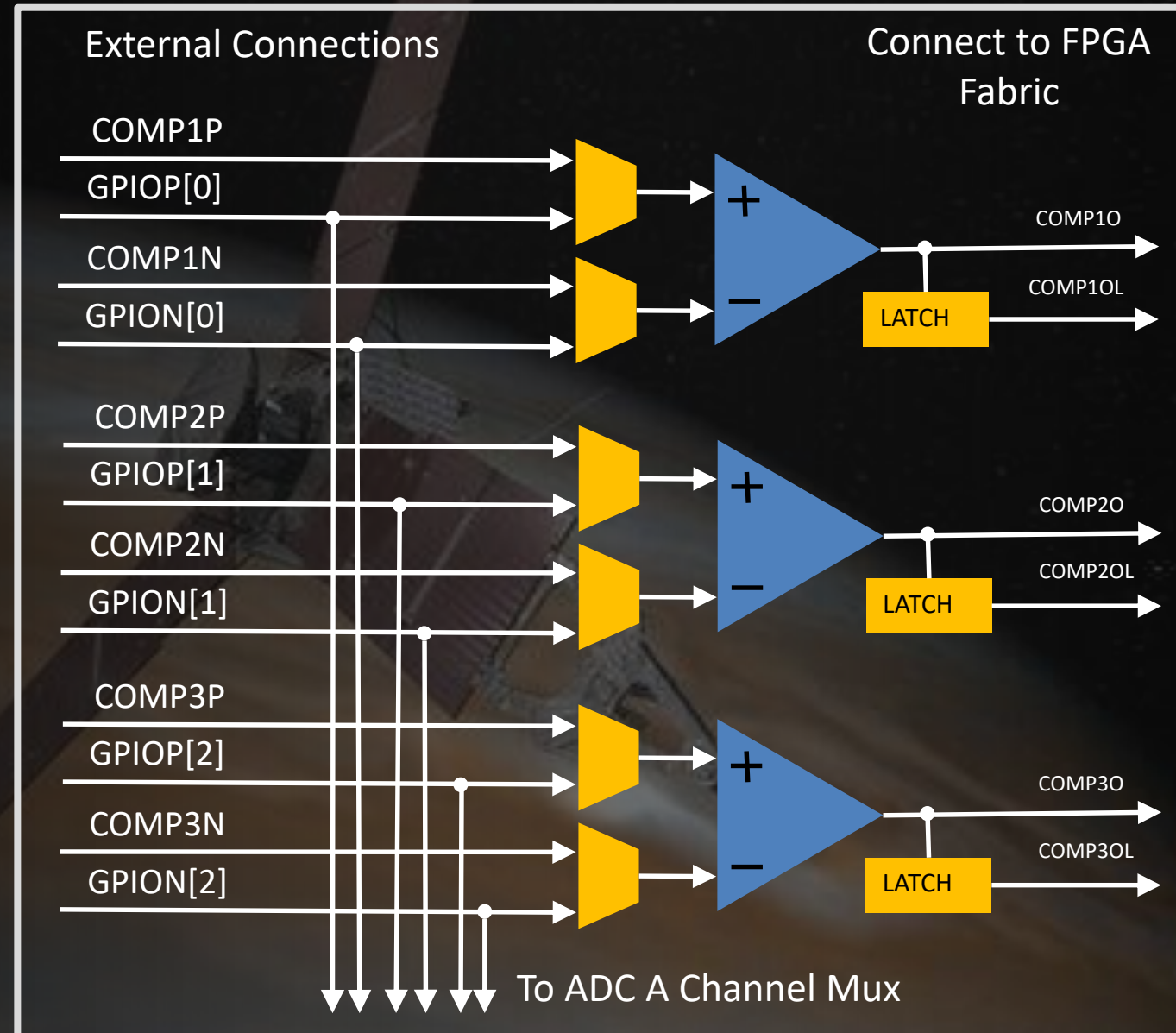
- Built-In Analog Features For Mixed Signal Sensing and Processing
- 2x (independent) ADCs per device
  - 1 MSPS, 12-bit SAR
- Simultaneous sampling
- 18 differential analog inputs
- 5 internal voltage rail inputs
- One internal temperature input
- Requires external V-Ref
  - 1.2 to 1.8 V



# Embedded Comparators

Certus™-NX-RT and CertusPro™-NX-RT

- Three continuous-time comparators
  - Shared GPIO to ADC A or,
  - Independent Analog Inputs
- Real time or latched outputs
- Requires external reference to compare with input signal
- For Telemetry, fault detection, level sensing and more



# Clocks - Resources and Routing

Certus™-NX-RT and CertusPro™-NX-RT

## High Performance Clock Distribution:

- Up to 64 Primary Clocks
- Four edge clocks per bank at bottom of device.
- Total 12 edge clocks.
  - Low Skew, high speed clock resources for I/O Logic

## Efficient clock logic modules:

- Clock dividers, Dynamic clock select, Dynamic clock control

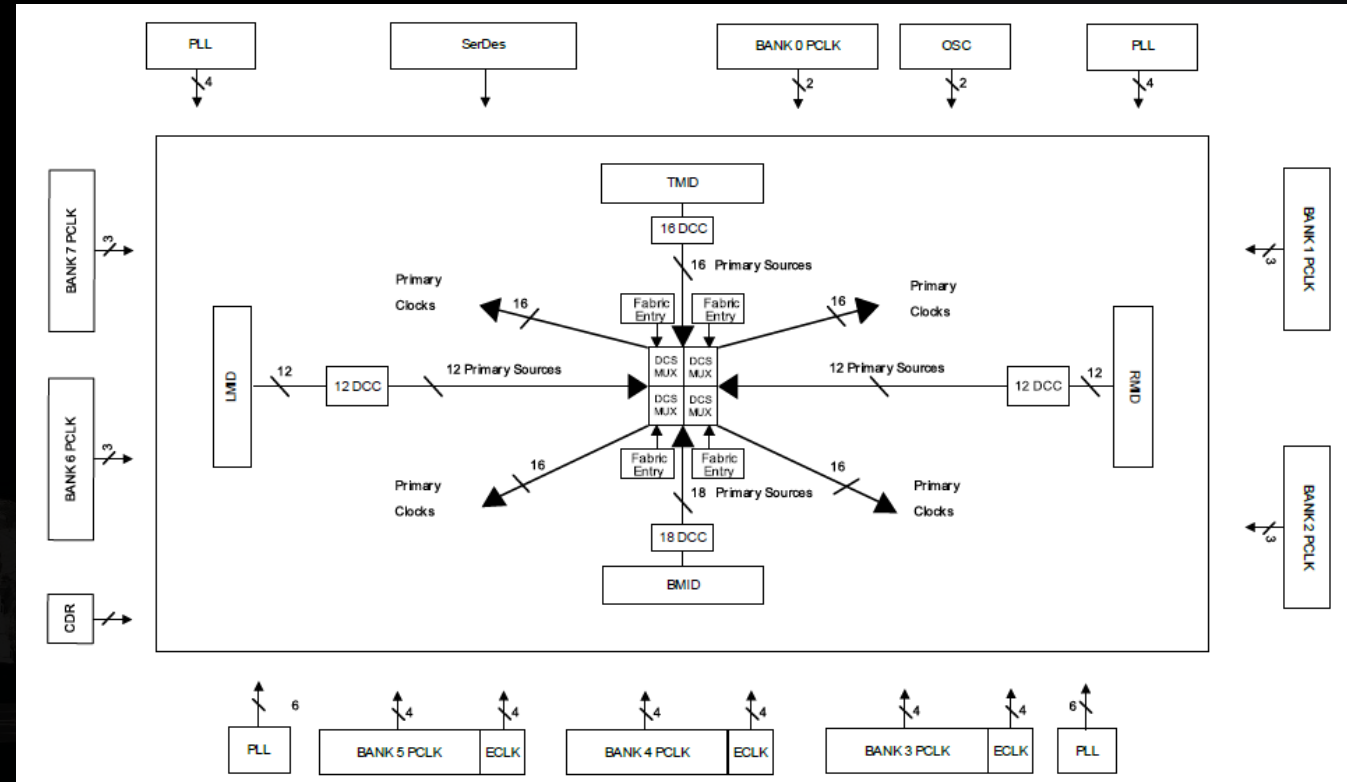
## sysCLOCK PLL:

- 3 PLLs in C-NX-RT, 4 PLLs in CP-NX-RT

2 DDR DLL for DDR memory and HP IO

## Internal Oscillators

- One high frequency and one low frequency clock osc

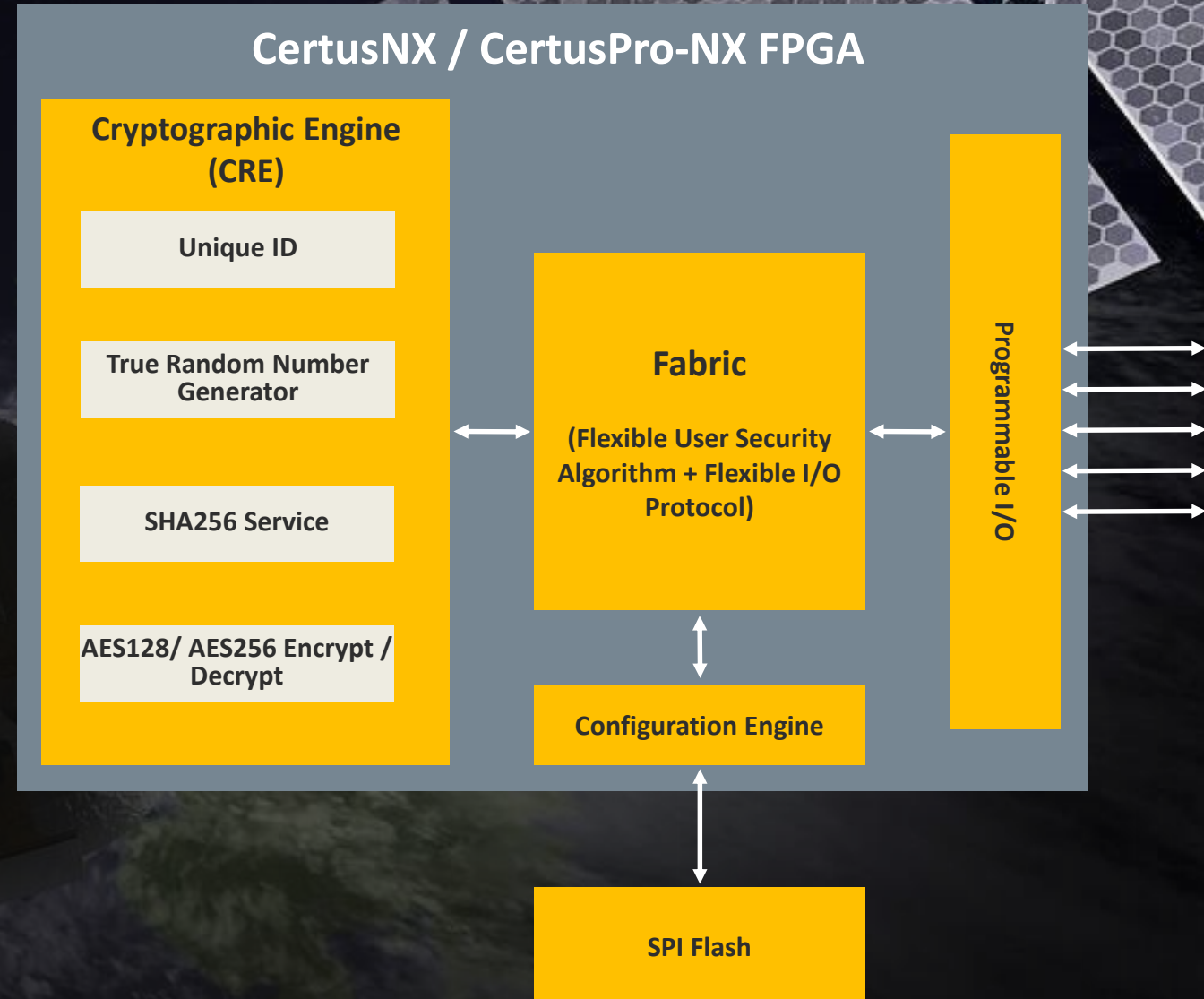


# Security Features

Certus™-NX-RT and CertusPro™-NX-RT

Built-in bitstream encryption and authentication for system integrity

- Bitstream security
  - ECDSA256 authentication
  - AES256 encryption
  - Radiant support enabled by default
- User mode security features
  - Access CRE functions thru fabric (using CRE IP)
  - Radiant support enabled upon request (under license control)
  - Unlimited reprogramming cycles



A night landscape featuring a dark, starry sky with a visible band of light, possibly the Milky Way, over a snow-covered mountain range and a dark road winding through the foreground. The scene is illuminated by a soft, ambient light, likely from the moon or distant stars.

# FRONTGRADE

## Support Hardware & Tools

# Comprehensive Ecosystem

Hardware, Software, Design Tools, IP

## Devices

### Certus™-NX-RT



#### FPGA Devices

- Flight devices
- Application Engineering Support
- Radiation reports
- Reliability and TCI summaries

#### Holistic SW, HW, Radiation Technical Support

- Frontgrade
- [www.Frontgrade.com](http://www.Frontgrade.com)

## Design Tools

### Lattice Radiant



#### Lattice Radiant® design SW

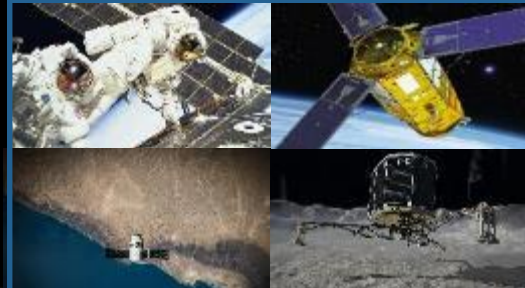
- Easy design navigation and debugging
- Powerful optimization tools that feature best in class algorithms
- Precise analysis tools for design, timing, and power analysis
- Complete closed-loop cross probing from physical to logical design implementation

#### SW Technical Support

- Frontgrade
- Extensive support at: [www.Latticesemi.com](http://www.Latticesemi.com)

## IP Libraries

### Frontgrade GRLIB



#### GRLIB FT-FPGA IP library with fault-tolerance features

- LEON series (UT700, GR712RC, and GR740) & NOEL-V RISC-V processors
- System peripherals
- Reference designs
- Communication controllers, including SpaceWire and SpaceFibre
- Cryptography accelerators

#### SW Technical Support

- Frontgrade
- [www.Gaisler.com](http://www.Gaisler.com)

### Lattice Propel



#### Propel – Analysis, compile and debug tools

- Includes Propel SW Dev. Tools and Propel Builder
- High productivity HW/SW debugging
- Drag and drop IP instantiation
- Correct by construction design methodology

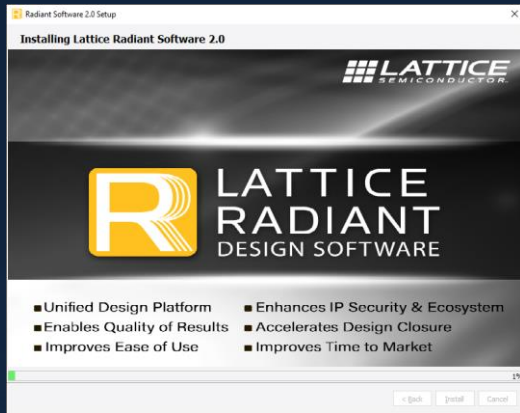
#### SW Technical Support

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# Lattice Radiant

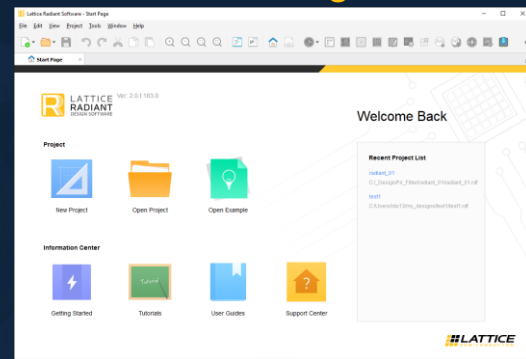
## Intuitive and Easy Design Experience

### Small-Fast Download & Installation

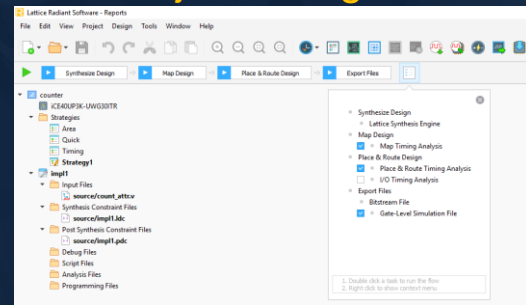


### Easy Navigation

#### Start Page



#### Project Navigator



### 1-Click Execution

#### Execution Toolbar



#### Report Panel

##### Reports

##### Project Summary

▶ Synthesis Reports

▼ Map Reports

✔ Map

✔ Map Resource Usage

✔ Map Timing Analysis

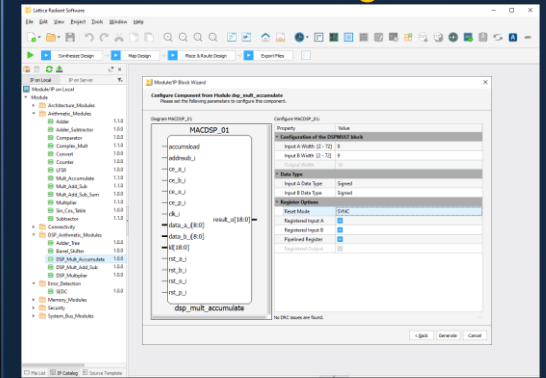
▶ Place & Route Reports

▶ Export Reports

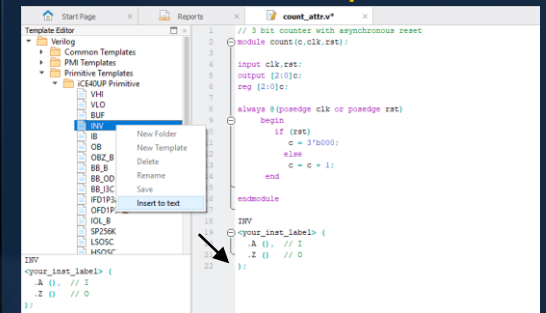
▶ Misc Reports

### Intuitive IP Assembly

#### IP Catalog



#### Source Template



# GRLIB Support

Certus™-NX-RT and CertusPro™-NX-RT

Milestone	Q1	Q2	Q3	Q4
Description	Initial support	GRLIB COM support Experimental FT-FPGA support	<a href="#">GR740-MINI board</a> Space SoC reference design	GRLIB FT-FPGA support <a href="#">Lattice Propel</a> integration
Functionality	Complete technology mapping and project file generation support.	Timing optimizations of GRLIB IP for Lattice FPGAs. Validation of processor IP on Lattice Nexus FPGAs PRE-built bitstreams: LEON3 - Certus™-NX Versa LEON3 - CertusPro™-NX.	GR740-MINI board with pre-built bitstream for CertusPro™-NX.	TENTATIVE- subject to execution of SEE test campaigns Design recommendations for radiation mitigation of SoC designs in Lattice FPGAs. <a href="#">Lattice Propel</a> integration of standalone IPs
IPs available (area figures in <a href="#">gplib area</a> )	<a href="#">CAN</a> , <a href="#">SPIMCTRL</a> , <a href="#">FTMCTRL</a> , <a href="#">SpaceWire</a> , <a href="#">GR1553B</a>	<a href="#">LEON3</a> , <a href="#">GRHSSL</a> , <a href="#">GRPCI2</a>		<a href="#">NOEL-V</a> (MC32 configuration)
Template designs	LEON3 in <a href="#">CrossLink-NX Evaluation Board</a> LEON3 in <a href="#">Certus™-NX Versa Evaluation Board</a>	LEON3 in <a href="#">CertusPro™ Versa Evaluation Board</a>	FPGA reference designs showing guidelines for a traditional SoC system for space applications. SoC for GR740-MINI board	NOEL-V in <a href="#">CertusPro™ Versa Evaluation Board</a>



# Evaluation Boards

Certus™-NX-RT and CertusPro™-NX-RT

## Certus™-NX-RT



Adiuvo Space Development board  
PMOD, Raspberry PI Pico



Lattice Versa Board  
DDR3, Ethernet, PCIe

## CertusPro™-NX-RT



Lattice Evaluation board  
Easy access to I/O and SerDes



Lattice Versa Evaluation board  
LPDDR4, 10G Ethernet, 1G Ethernet, PCIe

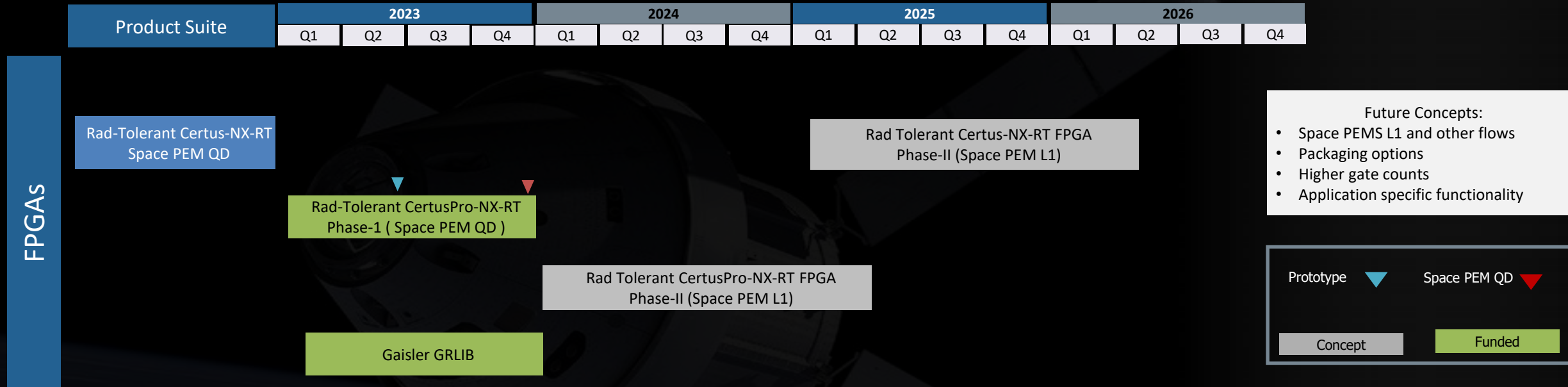
A night landscape photograph showing a dark road winding through a snowy, mountainous terrain under a starry sky. The Milky Way is visible in the dark blue sky. The image is partially obscured by a dark grey overlay on the right side.

# FRONTGRADE

## Roadmap

# Certus™/Pro-NX-RT FPGAs

## Roadmap and Introduction Schedule



### Certus-NX-RT

- Space Grade Automotive Parts Shipping **NOW!**
- Evaluation Boards – **Available NOW !**
- Radiation & Outgassing Reports Available

### CertusPro-NX-RT

- Q1 2023: Industrial grade devices
- Q1 2023 : Evaluation Boards
- Q4 2023: Space grade (Characterized purpose built lots)
  - Will include ATE test bring up to characterize TID in depth

# Frontgrade FPGA'S

Certus™-NX-RT and CertusPro™-NX-RT

Features	Lattice Automotive Grade	FRONTGRADE – Space PEM QD	FRONTGRADE – Space PEM L1
Baseline Electrical Performance & Qualification & Reliability Monitors	✓	✓	✓
Parts Material and Process Control agreement		✓	✓
Single Wafer lot Traceability		✓	✓
In-line Tin Lead Solder balling assembly		✓	✓
Outgassing reports		✓	✓
DPA Report		✓	✓
SEE Report		✓	✓
TID Radiation Lot acceptance testing per wafer lot		✓	✓
Temp Cycling			✓
X-Ray and CSAM			✓
Burn-In			✓
Multi-Temp Electrical Testing			✓
Added Qual Activity			✓

# Screening Flows - Abbreviated

Operations	Specification or Standard	PEM-INST-001	ECSS-Q-ST-60-13C	FRONTGRADE SOLUTIONS	
		Level 1	Grade 1	Space PEM L1	Space PEM QD
Single Wafer Lot Source	Internal/Vendor Specification			✓	✓
Temp Cycle	MIL-STD-883 TM1010 (-65°C to +150°C)	Cond B (or at manufacturer storage temp range, whichever is less); 20 cycles	10 Cycles @ Cond B (or at manufacturer storage temp range, whichever is less); 20 cycles	JESD22 A104; 20 cycles	Optional
Radiography	MIL-STD-883 TM2012	✓	✓	✓	Optional
Pre BI Electrical Test	Per Device Specification	25°C, Min, and Max	+25°C	25°C, -40°C, and 125°C	
Dynamic Burn-in	MIL-STD-883 TM1015	✓	✓	Per device specification	
Interim Electrical Test	Per Specification (+25°C)	✓		25°C, -40°C, and 125°C	
Static Burn-in (I or II)	MIL-STD-883 TM1015	✓		✓	
Final Electrical Test (+25°C)	Per Specification (+25°C)	✓	✓	✓	✓
Delta	Per Specification	✓		Per device specification	Per device specification
Cumulative PDA		5%		5%	
Final Electrical Test (Max Temp)	Per Specification (Max Temp)	✓	✓	✓	✓
Final Electrical Test (Min Temp)		✓	✓	✓	✓
External Visual	MIL-STD-883 TM 2009	✓	✓	✓	✓

A night landscape photograph showing a dark road winding through a snowy, mountainous terrain under a starry night sky. The Milky Way is visible in the upper portion of the frame.

# FRONTGRADE

## Radiation & Reliability

Presenter: Brian Baranski – Systems Architect

# Radiation Test Team & Locations

Certus™ -NX-RT

## Team

Melanie Berg : Principal Investigator , Scott Linton : Test Engineer, Matt Von Thun : Radiation Effects  
Brian Baranski : Systems Architect

## Heavy Ion

Texas A&M K500 Cyclotron 15MeV (05- Aug-2022)  
Texas A&M K500 Cyclotron 15MeV (17-Nov-2022)

## Proton

James M. Slater MD Proton Center, Loma Linda (17-Sep-2022)

## Total Ionizing Dose

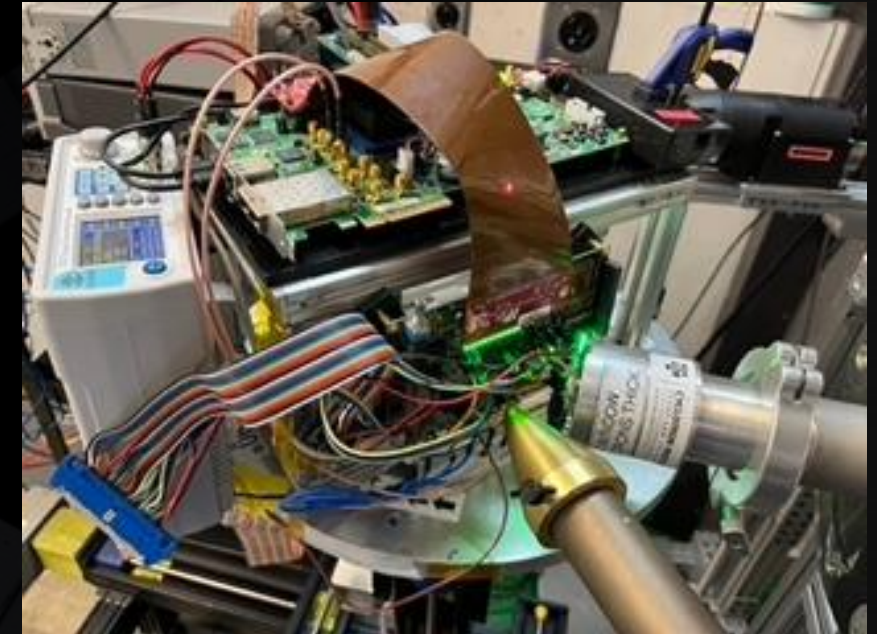
Radiation Test Solutions, Colorado Springs (30-Nov-2022)

## Test approach

*NASA Electronics Parts and Packaging (NEPP) FPGA SEU Test Guidelines:*  
[https://nepp.nasa.gov/files/23779/fpga\\_radiation\\_test\\_guidelines\\_2012.pdf](https://nepp.nasa.gov/files/23779/fpga_radiation_test_guidelines_2012.pdf)

## Radiation Test Group

Data shared during the February 2023 Consortium meeting chaired by Sandia



SEL Testing at Texas A&M

# Heavy Ion Testing

Certus™ -NX-RT

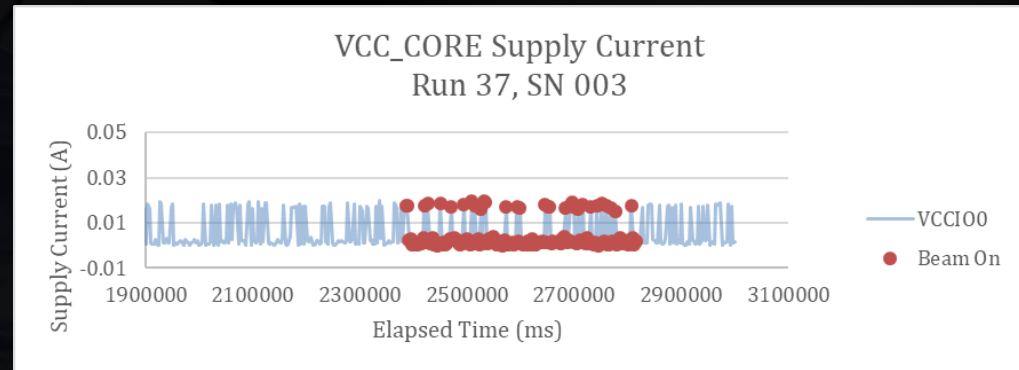
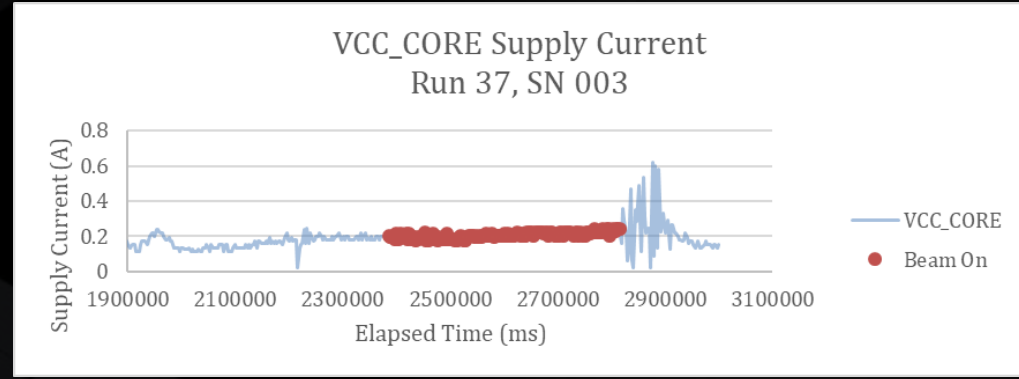
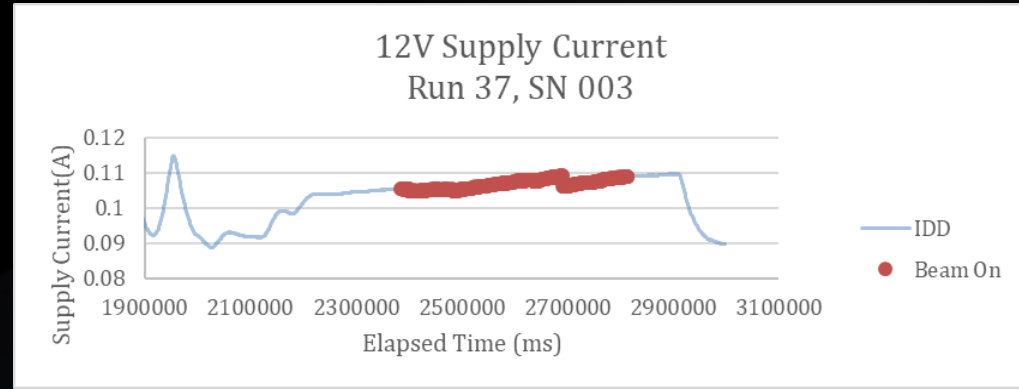
- Devices were irradiated with Xe, Kr, Ar, Ne, N ions at angles between 0 and 45 degrees with effective LETs ranging from 1.35 to 88.6 MeV·cm<sup>2</sup>/mg
- SEL immunity was verified at 125°C at max voltages to 80 MeV·cm<sup>2</sup>/mg
- Full report contains cross-sections for each of the below tests:
- Single Event Failure cross-section characterized on four designs:
  - Windowed Shift Register (WSR)/PLL
  - PCIe
  - ADC/Comparator
  - DDR3
- Single Event Upset cross-section characterized for:
  - Configuration Memory (CRAM)
  - Embedded SRAM (without EDAC)
  - Shift registers DFFs
- PCIe design was evaluated with and without the scrubber



# SEL Test Data

Certus™ -NX-RT

- No sustained current excursions observed indicating no SEL events. All testing performed at 125C
- Run 37 current plots shown as representative examples
- VCC Core dominates combined current

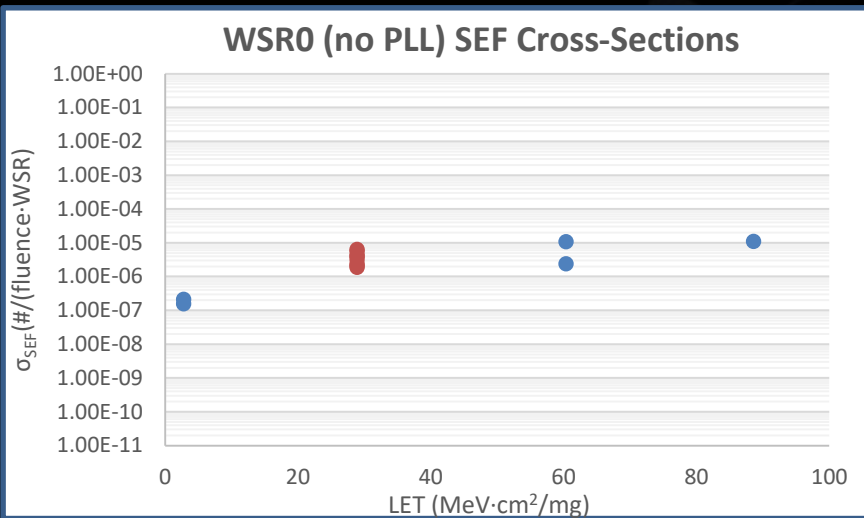


Session	Run #	SN	12V Vdd (V)	Internal Vdd(s) (V)	Ion	Eff. LET (MeV·cm <sup>2</sup> /mg)	Eff. Fluence (ions/cm <sup>2</sup> )	Latchup
Aug	1	1	13.2	Nom	Xe	88.6	1.0×10 <sup>7</sup>	No
Aug	2	2	13.2	Nom	Xe	88.6	1.0×10 <sup>7</sup>	No
Nov	37	3	13.2	+10%	Xe	80.2	1.0×10 <sup>7</sup>	No

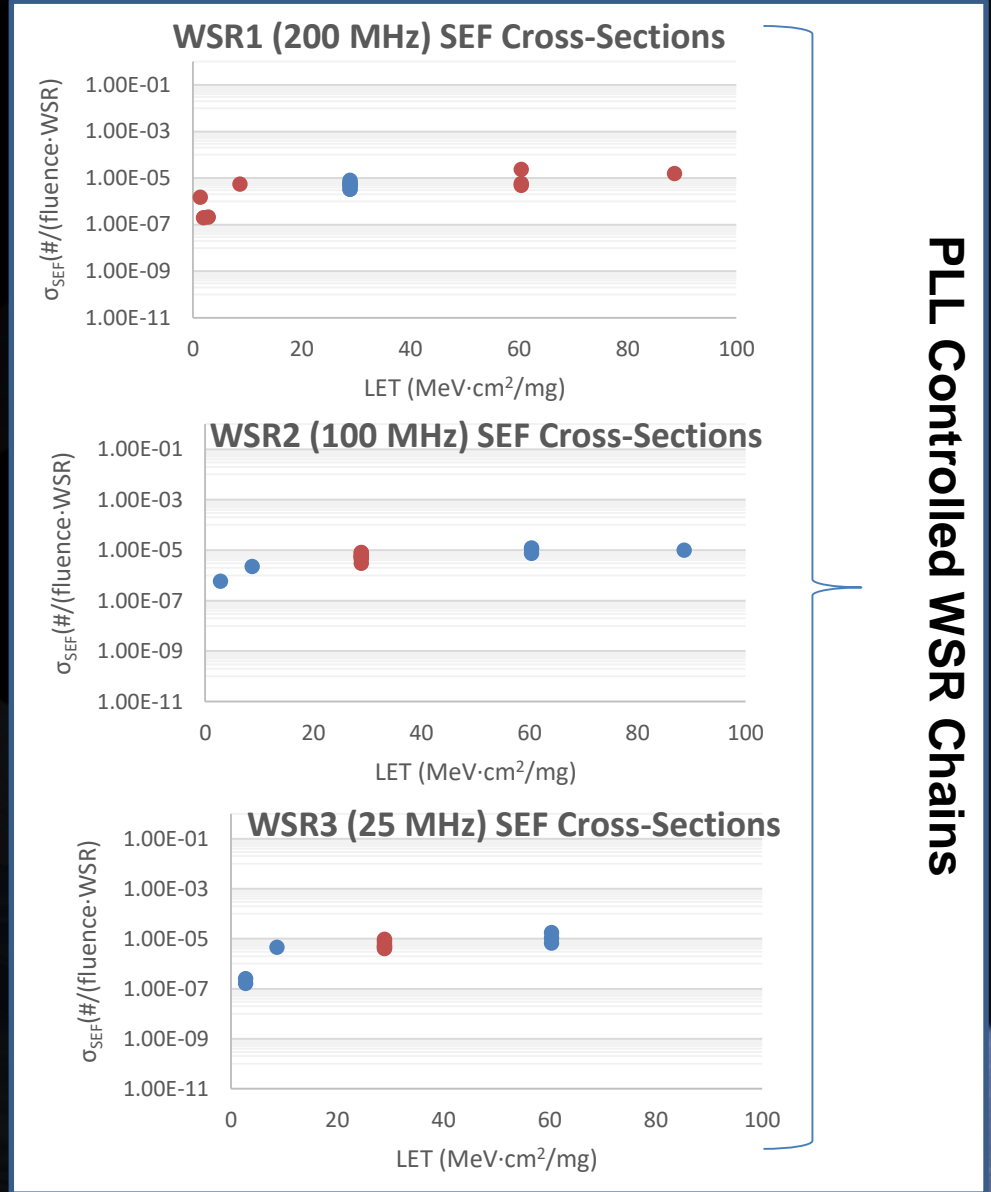
# Fabric DFF Operating SEU Cross-Section

Certus™ -NX-RT

- There are 400 DFFs per string. (SEF represents SEU in shift registers or configuration failures).
- PLL or frequency changes, do not significantly affect WSR SEF susceptibility.



No PLL clock is direct from clock pin + global buffer



PLL Controlled WSR Chains

Parameter	Comment
On-set LET ( $L_0$ )	$L_0 = 8.66 \text{ MeV} \cdot \text{cm}^2 / \text{mg}$ .
On-set ( $\sigma_0$ )	$\sigma_0 \approx 1.0 \times 10^{-11} (\# / \text{fluence} \cdot \text{DFF})$
Saturation LET ( $L_{sat}$ )	$8 \text{ MeV} \cdot \text{cm}^2 / \text{mg} < L_{sat} < 12 \text{ MeV} \cdot \text{cm}^2 / \text{mg}$
Saturation SEF cross section ( $\sigma_{sat}$ )	$\sigma_{sat} \approx 2.7 \times 10^{-8} (\# / \text{fluence} \cdot \text{DFF})$

# Configuration RAM

Certus™-NX-RT

- Error rates for configuration memory are very low
- There are 6.2E6 configuration bits in the Certus-NX-RT

### Best Fit Weibull

Shape	Width	Sat. X-sect	LETonset
0.8	80	5.5E-10	1.3

GEO Adams 90%      LEO-ISS Adams 90%

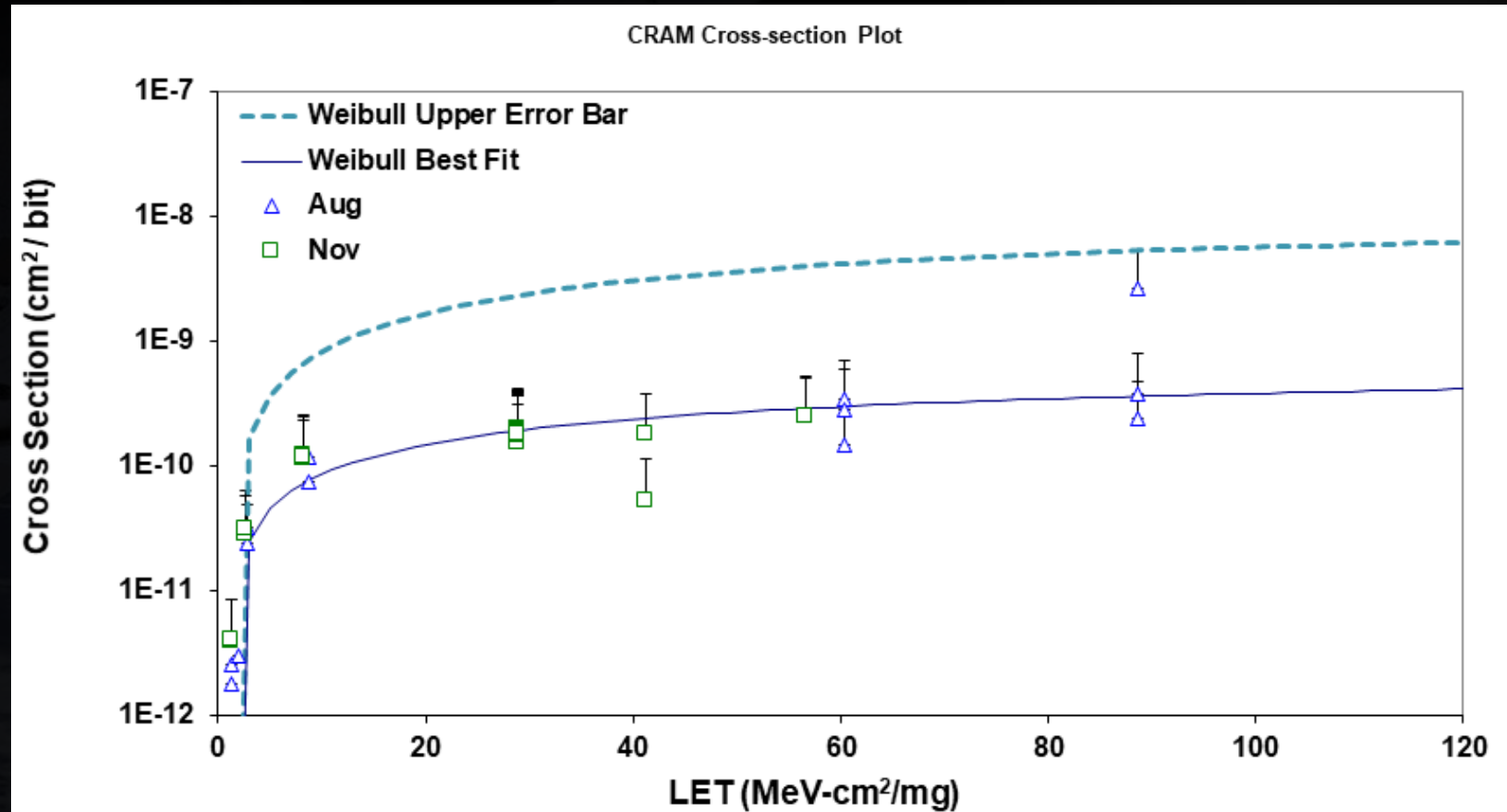
err/bit-day	err/bit-day
3.94E-10	5.54E-12

### Upper Error Bar Weibull

Shape	Width	Sat. X-sect	LETonset
1	80	8.0E-09	1.3

GEO Adams 90%      LEO-ISS Adams 90%

err/bit-day	err/bit-day
1.02E-08	4.91E-10



# TID Test Results

Certus™ -NX-RT

- 5 parts tested to 100krad(Si), 2 additional parts step stressed to 200krad(Si). See full report for details
- All seven devices passed the Windowed Shift Register functional tests, DC levels tests, rise/fall time tests to the 100krad(Si) specification level
- Above 100krad(Si) on step stress parts, effects of TID were observed on the VIL, VOL and VIH

Test	Qty	Voltage Bias	WSR	VIL	VIH	VOL	VOH
TID Step Read points	5	Nom + 5%	100k rad(Si)				
TID Specification	5	Nom + 5%	100 krad(Si)				
Lowest WSR failing TID	5	Nom + 5%	No fails	No fails	No fails	No fails	No fails
Highest WSR passing TID	5	Nom + 5%	100k	100k	100k	100k	100k
Lowest TID at which all Fail	5	Nom + 5%	No fails	No fails	No fails	No fails	No fails
Highest TID at which all Pass	5	Nom + 5%	100k	100k	100k	100k	100k

Test	Qty	Voltage Bias	WSR	VIL	VIH	VOL	VOH
TID Step Read points	2	Nom + 5%	30k, 60k, 100k, 150k, 200k rad(Si)				
TID Specification	2	Nom + 5%	100 krad(Si)				
Lowest WSR failing TID	2	Nom + 5%	No fails	200k	200k	200k	200k
Highest WSR passing TID	2	Nom + 5%	200k	150k	200k	150k	200k
Lowest TID at which all Fail	2	Nom + 5%	NA	200k	NA	200k	NA
Highest TID at which all Pass	2	Nom + 5%	200k	150k	150k	100k	150k

# Proton Testing

Certus™-NX-RT

- Devices exposed to proton energies of 25, 50, 100, 200 MeV
- Single Event Failure cross-section characterized on four designs:
  - PCIe with scrubbing
  - PCIe without scrubbing
  - WSR/PLL
  - ADC/Comparator
- Single Event Upset cross-section characterized for:
  - Configuration Memory (CRAM)
- Details of above in full report



# Configuration Memory (CRAM)

Certus™ -NX-RT

- Configuration cross-section data plotted as number upset cells divided by fluence and number of bits
- Data appear to be relatively flat across the tested range of proton energies

Nominal Fit Weibull			
Shape	Width	Sat. X-sect	LETonset
0.4	5	4.00E-16	1

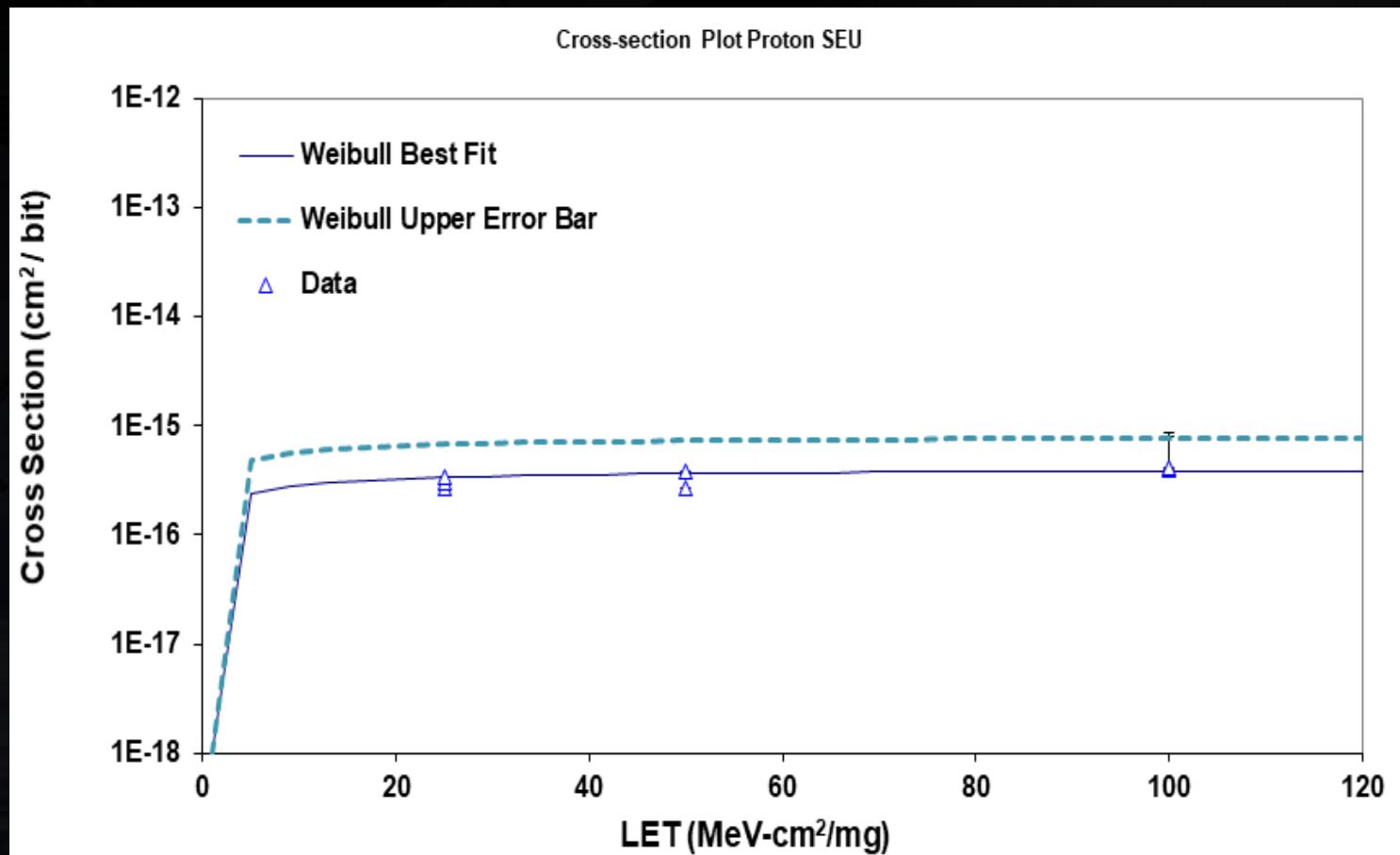
LEO	ISS
<u>err/bit·day</u>	
3.75E-10	

Upper Error Bar Weibull			
Shape	Width	Sat. X-sect	LETonset
0.4	5	8.00E-16	1

LEO	ISS
<u>err/bit·day</u>	
7.50E-10	



# QA/Reliability Assessment

Certus™-NX-RT

- Reliability Assessment of Technology/Product Complete
  - Technology documentation provided by Lattice
  - Assessed for 10 years @ 85°C lifetime:
    - HCI – Hot Carrier Injection
    - BTI – Bias Temperature Instability
    - TDDDB – Time Dependent Dielectric Breakdown
    - EM – Electromigration
    - IMD-TDDDB – Intermetallic Dielectric TDDDB
    - SM – Stress Migration
  - Technology qualification follows JEP001 Level 1 and Level 2

***All mechanisms passed for the target lifetime of 10 years***



# Product Qualification Summary

Certus™ -NX-RT

Test Name and Conditions	Hours or Cycles (Failures / Devices Tested)	
High Temperature Operating Life & Early Life Failure Rate JESD22-A108 125°C, Max Vdd  Typical Operating Conditions (Tjuse=55C, CL=60%, Ea=0.7eV): 23.6 FITs	500,500 Hrs	
	0 / 3616	
ESD	HBM	CDM
	Class 2 (2000 to < 4000V)	Class C1 (250 to < 500V)
Latch-Up	I-Test	Voltage Supply Overvoltage
	Class II (> +/- 100 mA)	Class II (> 1.5x Vdd)
Pre-Conditioning Level	MSL 3	
Temperature Cycling JESD22-A104, Condition B	700 cycles	
	0 / 75	
Temperature Humidity JESD22-A101, 85°C/85%	1000 hrs	
	0 / 75	
Temperature Humidity Bias JESD22-A101	1000 hrs	
	0 / 75	
High Temperature Storage Life JESD22-A103, Condition B, 150°C	1000 hrs	
	0 / 75	



# Key Takeaways

Certus™-NX-RT and CertusPro™-NX-RT

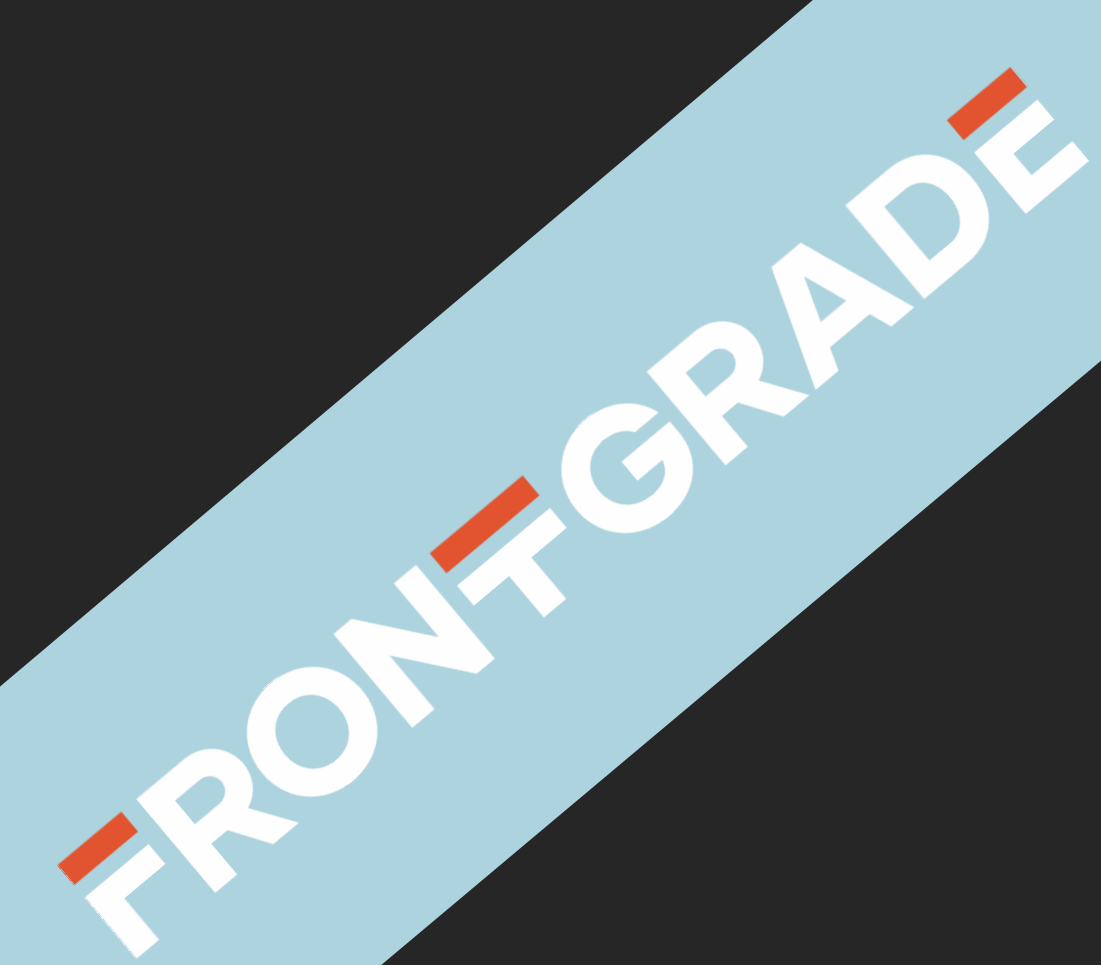
- Low power, small footprint and high performance FPGAs
- Built on reliable and radiation tolerant 28nm FD-SOI
- 100krad(Si) TID, SEL immune @ 80 MeV·cm<sup>2</sup>/mg and 125C
- Frontgrade reliability, radiation and application engineering support
- GRLIB IP Library support
- Certus-NX-RT available now with 2 week leadtimes
- CertusPro-NX-RT available Q4 2023





# FRONTGRADE

## Q&A



THANK YOU